

IN THE SPECIFICATION

Page 3, line 6 through line 25, please replace the paragraph with the following:

BRIEF SUMMARY OF THE INVENTION

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A semiconductor integrated circuit device according to an embodiment of the present invention comprises: a first semiconductor substrate, in which, a memory cell array including a plurality of nonvolatile semiconductor memory cells, a plurality of bit lines electrically connected to the memory cell array, a plurality of word lines electrically connected to the memory cell array, a plurality of input terminals, and a plurality of transfer gate transistors each having one end electrically connected to a corresponding one of the word lines and another end electrically connected to a corresponding one of the input terminals, are provided; and a second semiconductor substrate, in which, a plurality of output terminals electrically connected to the input terminals of the first semiconductor substrate, and a word line control circuit configured to control the word lines and electrically connected to the output terminals, are provided.

Page 3, line 26 through Page 4, line 12, please replace the paragraph with the following:

a2
A nonvolatile semiconductor memory ~~system~~ package according to an embodiment of the present invention comprises: a memory having a memory cell array including a plurality of nonvolatile semiconductor memory cells; a control portion configured to control the memory; a network interface connectable to a network; a file management portion connected to the network interface configured to ~~manages~~ manage a ~~relation~~ relationship between a data file given from the network and an address of the memory cell array; and a memory interface connected to the file management portion configured to convert a signal given from the network to a signal which is capable of being used at the control portion.

Page 4, line 13 through line 27, please replace the paragraph with the following:

Q³ A nonvolatile semiconductor memory device according to an embodiment of the present invention comprises: a first semiconductor substrate, in which, a memory having a memory cell array including a plurality of nonvolatile semiconductor memory cells, is provided; and a second semiconductor substrate, in which, a control portion configured to control the memory, a network interface connectable to a network, a file management portion connected to the network interface configured to ~~manages~~ manage a relation between a data file given from the network and an address of the memory cell array, and a memory interface connected to the file management portion configured to convert a signal given from the network to a signal which is capable of being used at the control portion, are provided.